

# U.2 SSD

## 3TG6-P Series

**Customer:** \_\_\_\_\_

**Customer**

**Part**

**Number:** \_\_\_\_\_

**Innodisk**

**Part**

**Number:** \_\_\_\_\_

**Innodisk**

**Model Name:** \_\_\_\_\_

**Date:** \_\_\_\_\_

<b>Innodisk Approver</b>	<b>Customer Approver</b>

**Total Solution For  
Industrial Flash Storage**

**Features:**

- PCIe Gen.3 x 4, NVMe SSD
- Kioxia 3D TLC NAND
- U.2 SSD 3TG6-P
- Wide-temperature
- iPowerguard
- iDataguard
- Dynamic Thermal Management
- Hybrid Write

**Performance:**

- Sequential Read up to 3,100 MB/s
- Sequential Write up to 2,600 MB/s

**Power Requirements:**

Input Voltage:	+12 DC +- 5%
Max Operating Wattage:	7.53W
Idle Wattage:	3.29W

**Reliability:**

Capacity	TBW	DWPD
128GB	168	1.2
256GB	422	1.4
512GB	766	1.4
1TB	1793	1.6
2TB	4162	1.9

Data Retention	1 Year
Warranty	3 Years

For warranty details, please refer to:

[https://www.innodisk.com/en/support\\_and\\_service/warrant](https://www.innodisk.com/en/support_and_service/warrant)

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## REVISION HISTORY

Revision	Description	Date
V1.0	First release	Aug., 2021
V1.1	Revise LBA and user capacity	Sep., 2021

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# 1. Product Overview

## 1.1 Introduction of Innodisk U.2 SSD 3TG6-P

Innodisk U.2 SSD 3TG6-P is an NVM Express SSD designed as PCIe SFF-8639 module with PCIe interface and 3D TLC NAND Flash. U.2 SSD 3TG6-P supports PCIe Gen III x4, and it is compliant with NVMe 1.3 providing excellent performance. With sophisticated error detection and correction (ECC) functions, the module can ensure full End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash.

Innodisk U.2 SSD 3TG6-P provides ultra-speed and high IOPS and offers maximum capacity up to 2TB, making the SSD optimal for server and heavy data workload applications.

**CAUTION** *TRIM must be enabled.*

*TRIM enables SSD's controller to skip invalid data instead of moving. It can free up significant amount of resources, extends the lifespan of SSD by reducing erase, and write cycles on the SSD. Innodisk's handling of garbage collection along with TRIM command improves write performance on SSDs.*

## 1.2 Product View and Models

Innodisk U.2 SSD 3TG6-P is available in follow capacities within 3D TLC flash ICs.

U.2 (P80) 3TG6-P 128GB

U.2 (P80) 3TG6-P 256GB

U.2 (P80) 3TG6-P 512GB

U.2 (P80) 3TG6-P 1TB

U.2 (P80) 3TG6-P 2TB



**Figure 1: Innodisk U.2 SSD 3TG6-P**

## 1.3 PCIe Interface

Innodisk U.2 SSD 3TG6-P supports PCIe Gen III interface and compliant with NVMe 1.3. U.2 SSD 3TG6-P can work under PCIe Gen 1, Gen 2 and Gen 3.

Most of operating system includes NVMe in-box driver now. For more information about the driver support in each OS, please visit <http://nvmeexpress.org/resources/drivers>.



## 2. Product Specifications

### 2.1 Capacity and Device Parameters

U.2 SSD 3TG6-P device parameters are shown in Table 1.

**Table 1: Device parameters**

Capacity	Cylinders	Heads	Sectors	LBA	User Capacity(MB)
128GB	16383	16	63	234441648	114473
256GB	16383	16	63	468862128	228937
512GB	16383	16	63	937703088	457863
1TB	16383	16	63	1875385008	915715
2TB	16383	16	63	3750748848	1831420

### 2.2 Performance

Burst Transfer Rate: 32.0Gbps

**Table 2: Performance - 64 layers 3D TLC**

Capacity	Unit	128GB	256GB	512GB	1TB	2TB
Sequential Read (max.)	MB/s	1,200	2,600	3,000	3,100	3,100
Sequential Write (max.)		520	1,000	2,000	2,500	2,600
Sustained Sequential Read (Avg.)***		720	1,200	1,360	1,360	1,370
Sustained Sequential Write (Avg.)***		170	330	670	1,170	1,440
4KB Random** Read (Q8T8)	IOPS	79,000	154,000	260,000	410,000	520,000
4KB Random** Write (Q8T8)		68,000	251,000	469,000	517,000	539,000

Note: \* Performance results are measured in Room Temperature with Out-of-Box devices and may vary depending on overall system setup. In addition, 3TG6-P series adopt hybrid mode which enables SLC Cache followed by TLC direct write to strike balance between burst performance and steady overall stability.

Note: \*\* Performance results are based on CrystalDiskMark 6.0.2 with file size 1000MB. Unit of 4KB items is I.O.P.S.

Note: \*\*\* Performance results are based on AIDA 64 v5.98 with block size 1MB of Linear Read & Write Test Item.

## 2.3 Electrical Specifications

### 2.3.1 Power Requirement

**Table 3: Innodisk U.2 SSD 3TG6-P Power Requirement**

Item	Symbol	Rating	Unit
Input voltage	V <sub>IN</sub>	+12 DC +- 5%	V

### 2.3.2 Power Consumption

**Table 4: Power Consumption**

Mode	Power Consumption (W)
Read(rms.)	6.46
Write(rms.)	7.53
Idle(rms.)	3.29
Power-on peak	16.53

\* Target: 2TB U.2 SSD 3TG6-P

Note: Current results may vary depending on system components and power circuit design. Please refer to the test report for other capacities

## 2.4 Environmental Specifications

### 2.4.1 Temperature Ranges

**Table 5: Temperature range for U.2 SSD 3TG6-P**

Temperature	Range
Operating	Standard Grade: 0°C to +70°C Industrial Grade: -40°C ~ +85°C
Storage	-40°C ~ +85°C

### 2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

### 2.4.3 Shock and Vibration

**Table 6: Shock/Vibration Testing for U.2 SSD 3TG6-P**

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 60068-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 60068-2-27

### 2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various U.2 SSD 3TG6-P configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- **Failure Rate:** The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.

- **Mean Time between Failures (MTBF):** A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

**Table 7: U.2 SSD 3TG6-P MTBF**

Product	Condition	MTBF (Hours)
Innodisk U.2 SSD 3TG6-P	Telcordia SR-332 GB, 25°C	>3,000,000

## 2.5 CE and FCC Compatibility

U.2 SSD 3TG6-P conforms to CE and FCC requirements.

## 2.6 RoHS Compliance

U.2 SSD 3TG6-P is fully compliant with RoHS directive.

## 2.7 Reliability

**Table 8: U.2 SSD 3TG6-P TBW**

Parameter	Value	
Flash endurance	3,000 P/E cycles	
Error Correct Code	Support (LDPC)	
Data Retention	Under 40°C: 10 Yeas at initial NAND Status (PE cycles under 100) 1 Years at NAND Life End (PE cycles reach 3,000)	
<b>TBW* (Total Bytes Written) Unit: TB</b>		
<b>Capacity</b>	<b>Sequential workload</b>	<b>Client workload</b>
128GB	340	168
256GB	680	422
512GB	1363	766
1TB	2727	1793
2TB	5454	4162
* Note:		
1. Sequential: Mainly sequential write are estimated by PassMark Burnin Test.		
2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK. (The capacity lower than 64GB client workload is not specified in JEDEC219A, the values are estimated.)		
3. Based on out-of-box performance.		

## 2.8 Transfer Mode

U.2 SSD 3TG6-P support following transfer mode:

PCIe Gen III 4 GB/s

PCIe Gen II 2 GB/s

PCIe Gen I 1 GB/s

## 2.9 Pin Assignment

Innodisk U.2 SSD 3TG6-P follows standard SFF-8639 spec as below. Mechanical details are documented in SFF-8639: Multifunction 6X Unshielded Connector.

**Table 9: Innodisk U.2 SSD 3TG6-P Pin Assignment**

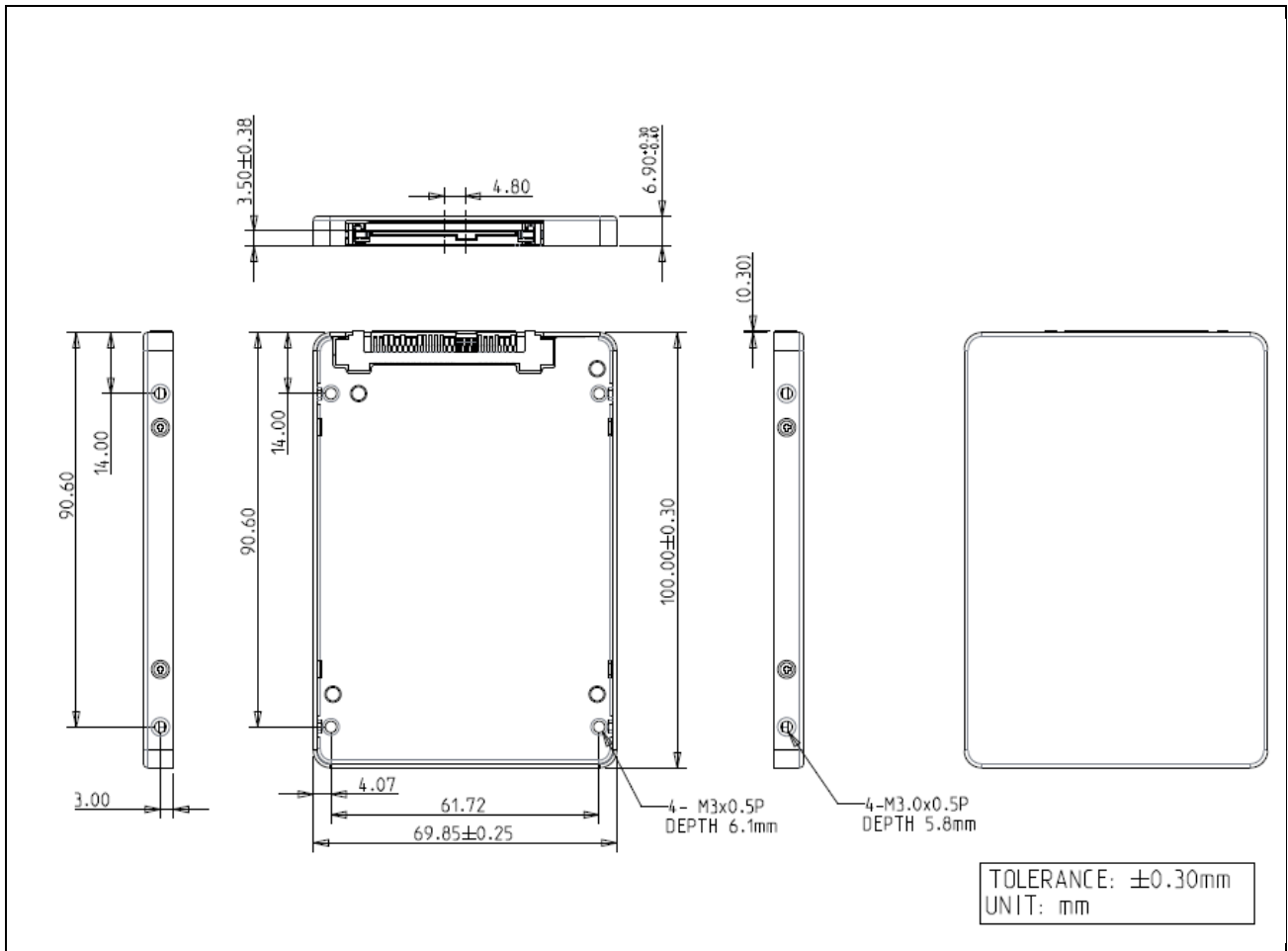
Pin	Mate	Name
P1	3rd	WAKE#
P2	3rd	-
P3	2nd	PWRDIS
P4	1st	IfDet#
P5	2nd	Ground
P6	2nd	Ground
P7	2nd	-
P8	3rd	-
P9	3rd	-
P10	2nd	-
P11	3rd	ACTIVITY#
P12	1st	Ground
P13	2nd	+12V Precharge
P14	3rd	+12V
P15	3rd	+12V
S1	2nd	Ground
S2	3rd	-
S3	3rd	-
S4	2nd	Ground
S5	3rd	-
S6	3rd	-
S7	2nd	Ground
S8	2nd	Ground
S9	3rd	-
S10	3rd	-
S11	2nd	Ground
S12	3rd	-
S13	3rd	-
S14	2nd	Ground
S15	3rd	-
S16	2nd	Ground

S17	3rd	PETp1
<b>Pin</b>	<b>Mate</b>	<b>Name</b>
S18	3rd	PETn1
S19	2nd	Ground
S20	3rd	PERn1
S21	3rd	PERp1
S22	2nd	Ground
S23	3rd	PETp2
S24	3rd	PETn2
S25	2nd	Ground
S26	3rd	PERn2
S27	3rd	PERp2
S28	2nd	Ground
E1	3rd	-
E2	3rd	-
E3	3rd	-
E4	3rd	-
E5	3rd	PERST#
E6	3rd	-
E7	3rd	RefClk0+
E8	3rd	RefClk0-
E9	2nd	Ground
E10	3rd	PETp0
E11	3rd	PETn0
E12	2nd	Ground
E13	3rd	PERn0
E14	3rd	PERp0
E15	2nd	Ground
E16	3rd	-
E17	3rd	PETp3
E18	3rd	PETn3
E19	2nd	Ground
E20	3rd	PERn3
E21	3rd	PERp3
E22	2nd	Ground
E23	3rd	-
E24	3rd	-
E25	3rd	-

**Table 10: Innodisk U.2 SSD 3TG6-P LED indicator**

LED Color	Function
Green	Power on
	Access

## 2.10 Mechanical Dimensions



**Figure 2: Innodisk U.2 SSD 3TG6-**

### 2.11 Assembly Weight

An Innodisk U.2 SSD 3TG6-P within NAND flash ICs, 128GB's weight is 7 grams approximately.

### 2.12 Seek Time

Innodisk U.2 SSD 3TG6-P is not a magnetic rotating design. There is no seek or rotational latency required.

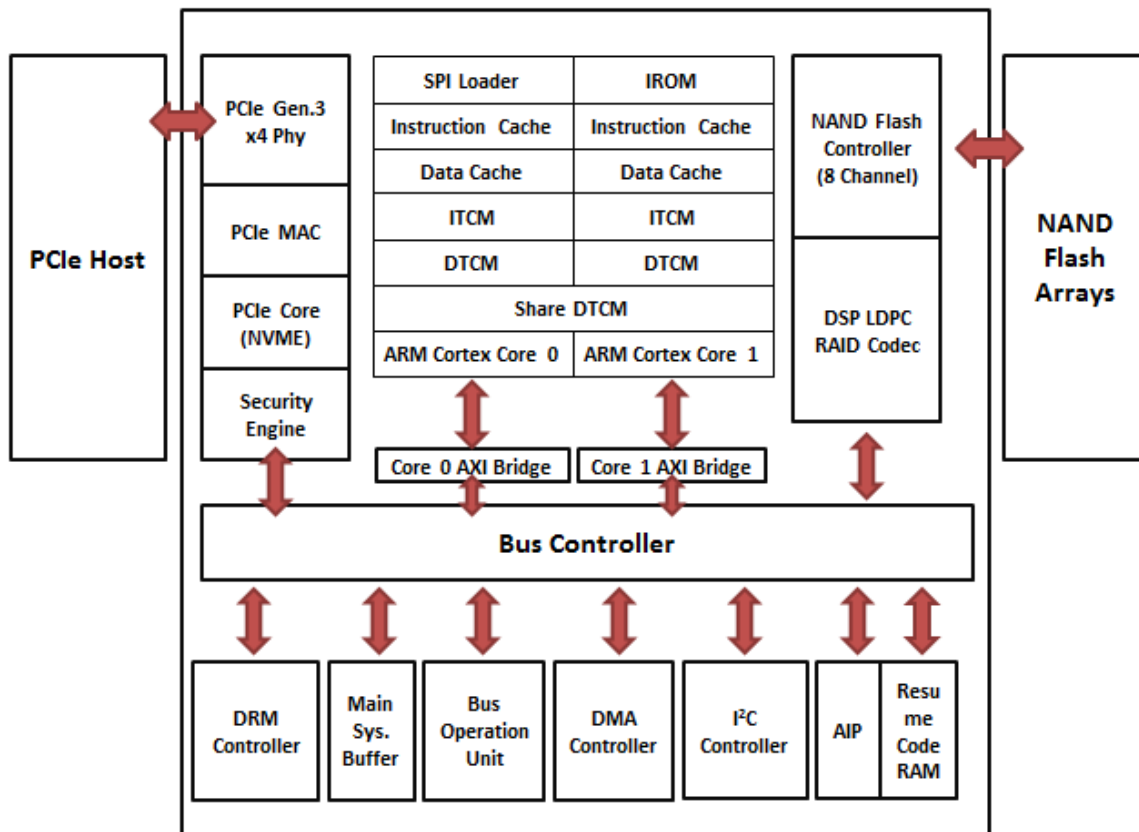
### 2.13 NAND Flash Memory

Innodisk U.2 SSD 3TG6-P uses 3D TLC NAND flash memory, which is non-volatility, high reliability and high speed memory storage.

# 3. Theory of Operation

## 3.1 Overview

Figure 2 shows the operation of Innodisk U.2 SSD 3TG6-P from the system level, including the major hardware blocks.



**Figure 3: Innodisk U.2 SSD 3TG6-P Block Diagram**

Innodisk U.2 SSD 3TG6-P integrates a PCIe Gen III x4 controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard NVM protocol. Communication with the flash device(s) occurs through the flash interface.

## 3.2 PCIe Gen III x4 Controller

Innodisk U.2 SSD 3TG6-P is a PCIe Gen IIx4 controller is compliant with NVMe 1.3, up to 32.0Gbps transfer speed. Also it is compliant with PCIe Gen 1, Gen 2 and Gen 3 specification. The controller supports up to 8 channels for flash interface.

### 3.3 Error Detection and Correction

Innodisk U.2 SSD 3TG6-P is designed with hardware LDPC ECC engine with hard-decision and soft-decision decoding. Low-density parity-check (LDPC) codes have excellent error correcting performance close to the Shannon limit when decoded with the belief-propagation (BP) algorithm using soft-decision information.

### 3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the **erase cycle limit** or **write endurance limit** and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk U.2 SSD 3TG6-P uses a combination of two types of wear leveling- dynamic and static wear leveling- to distribute write cycling across an SSD and balance erase count of each block, thereby extending flash lifetime.

### 3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

### 3.6 iData Guard

Innodisk's iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to the SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk's iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

### 3.7 Garbage Collection/TRIM

Garbage collection and TRIM technology is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.



### 3.8 End to End Data Path Protection

End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash. In the transmission path, no matter in or out, all buffer and storage implement Error Code Correction that optimizes the data integrity in the whole transmission of SSD.

### 3.9 Thermal Management

U.2 SSD 3TG6-P has built-in thermal sensor which can detect environment temperature of SSD. In the meantime, firmware will monitor the thermal sensor to prevent any failure of overheating. During extreme temperature, firmware will adjust the data transfer behavior to maintain the SSD’s reliable operation.

### 3.10 Die RAID

Die RAID is a controller function which leveraged user capacity to back up the data in NAND flash. Die RAID supported can ensure the user data in the NAND Flash more consistent in certain scenario. Innodisk M.2 (P80) 3TG6-P series is default enable the Die RAID function for the industrial application.

### 3.11 SLC Cache

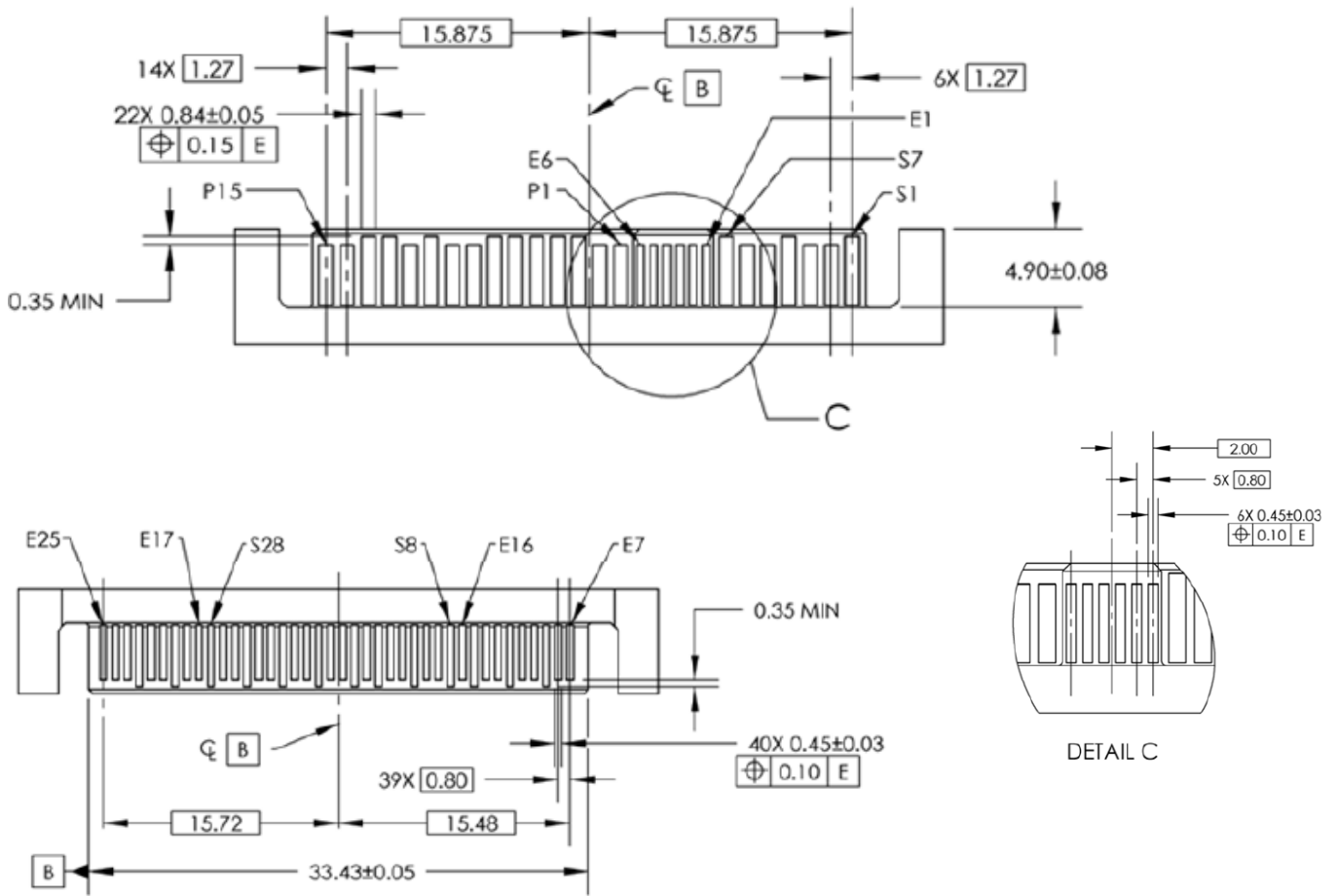
3TG6-P series adopt hybrid mode which enables SLC Cache up to 3% of total user capacity followed by TLC direct write to strike balance between burst performance and steady overall stability. The SLC Cache buffer size are defined as table below.

**Table 11: U.2 SSD 3TG6-P SLC cache**

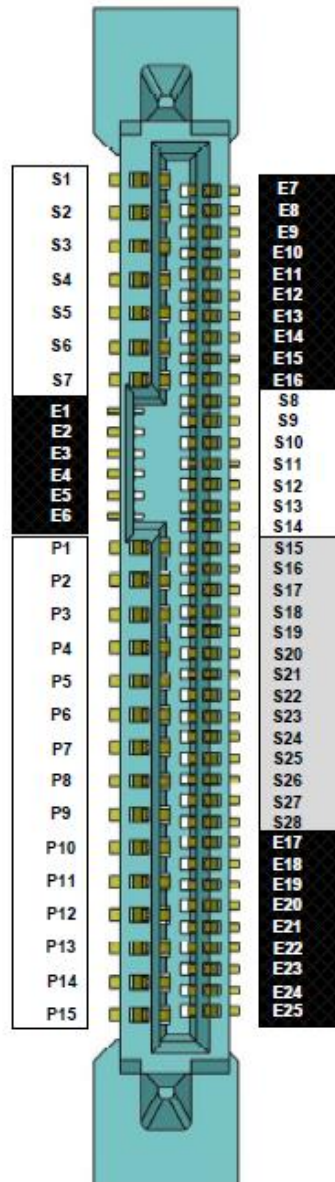
Capacity	128GB	256GB	512GB	1TB	2TB
SLC cache (GB)	3.84	7.68	15.36	30.72	61.44
SLC cache (%)	3	3	3	3	3

# 4. Installation Requirements

## 4.1 U.2 SSD 3TG6-P Pin Directions



**Figure 4: Device Signal Segment Power Segment**



**Figure 5: Signal Segment and Power Segment(Host/cable side)**

## 4.2 Electrical Connections for U.2 SSD 3TG6-P

U.2 SSD 3TG6-P follows standard SFF-8639 spec, Mechanical details are documented in SFF-8639: Multifunction 6X Unshielded Connector, it is a total of 68 contacts, not all contacts may be utilized. U.2 SSD 3TG6-P only support PCIe interface, see more details in *2.9 Pin Assignment*.

## 4.3 Device Drive

U.2 (P80) 3TG6-P is compliant with NVMe 1.3. Both Operation System and BIOS should include NVMe driver to compatible with NVMe device. Nowadays, most of OS includes NVMe in-box driver now. For more information about the driver support in each OS, please visit the website <http://nvmexpress.org/resources/drivers>. For BIOS NVMe driver support please contact with motherboard manufacturers.

## 5. SMART / Health Information

This log page is used to provide SMART and general health information. The information provided is over the life of the controller and is retained across power cycles. More details about Set Features command; please refer to NVM Express 1.3

### 5.1 Get Log Page(Log Identifier 02h)

Innodisk 3TG6-P series SMART / Health Information Log are listed in following table.

**Table 12: Get Log Page – SMART / Health Information Log**

Bytes	Description														
0	<p><b>Critical Warning:</b> This field indicates critical warnings for the state of the controller. Each bit corresponds to a critical warning type; multiple bits may be set. If a bit is cleared to '0', then that critical warning does not apply. Critical warnings may result in an asynchronous event notification to the host. Bits in this field represent the current associated state and are not persistent.</p> <table border="1"> <thead> <tr> <th>Bit</th> <th>Definition</th> </tr> </thead> <tbody> <tr> <td>00</td> <td>If set to '1', then the available spare space has fallen below the threshold.</td> </tr> <tr> <td>01</td> <td>If set to '1', then a temperature is above an over temperature threshold or below an under</td> </tr> <tr> <td>02</td> <td>If set to '1', then the NVM subsystem reliability has been degraded due to significant media related</td> </tr> <tr> <td>03</td> <td>If set to '1', then the media has been placed in read only mode.</td> </tr> <tr> <td>04</td> <td>If set to '1', then the volatile memory backup device has failed. This field is only valid if the</td> </tr> <tr> <td>07:05</td> <td>Reserved</td> </tr> </tbody> </table>	Bit	Definition	00	If set to '1', then the available spare space has fallen below the threshold.	01	If set to '1', then a temperature is above an over temperature threshold or below an under	02	If set to '1', then the NVM subsystem reliability has been degraded due to significant media related	03	If set to '1', then the media has been placed in read only mode.	04	If set to '1', then the volatile memory backup device has failed. This field is only valid if the	07:05	Reserved
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02	If set to '1', then the NVM subsystem reliability has been degraded due to significant media related														
03	If set to '1', then the media has been placed in read only mode.														
04	If set to '1', then the volatile memory backup device has failed. This field is only valid if the														
07:05	Reserved														
2:1	<p><b>Composite Temperature:</b> Contains a value corresponding to a temperature in degrees Kelvin that represents the current composite temperature of the controller and namespace(s) associated with that controller. The manner in which this value is computed is implementation specific and may not represent the actual temperature of any physical point in the NVM subsystem. The value of this field may be used to trigger an asynchronous event.</p>														

	Warning and critical overheating composite temperature threshold values are reported by the WCTEMP and CCTEMP fields in the Identify Controller data structure.
3	<b>Available Spare:</b> Contains a normalized percentage (0 to 100%) of the remaining spare capacity available.
4	<b>Available Spare Threshold:</b> When the Available Spare falls below the threshold indicated in this field, an asynchronous event completion may occur. The value is indicated as a normalized percentage (0 to 100%).
5	<b>Percentage Used:</b> Contains a vendor specific estimate of the percentage of NVM subsystem life used based on the actual usage and the manufacturer's prediction of NVM life. A value of 100 indicates that the estimated endurance of the NVM in the NVM subsystem has been consumed, but may not indicate an NVM subsystem failure. The value is allowed to exceed 100. Percentages greater than 254 shall be represented as 255. This value shall be updated once per power-on hour (when the controller is not in a sleep state).  Refer to the JEDEC JESD218A standard for SSD device life and endurance measurement techniques.
31:6	<b>Reserved</b>
47:32	<b>Data Units Read:</b> Contains the number of 512 byte data units the host has read from the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes read) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data read to 512 byte units.  For the NVM command set, logical blocks read as part of Compare and Read operations shall be included in this value.
63:48	<b>Data Units Written:</b> Contains the number of 512 byte data units the host has written to the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes written) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data written to 512 byte units.  For the NVM command set, logical blocks written as part of Write operations shall be included in this value. Write Uncorrectable commands shall not impact this value.
79:64	<b>Host Read Commands:</b> Contains the number of read commands completed by the controller.  For the NVM command set, this is the number of Compare and Read commands.

95:80	<p><b>Host Write Commands:</b> Contains the number of write commands completed by the controller.</p> <p>For the NVM command set, this is the number of Write commands.</p>
111:96	<p><b>Controller Busy Time:</b> Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O Queue (specifically, a command was issued via an I/O Submission Queue Tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O Completion Queue). This value is reported in minutes.</p>
127:112	<p><b>Power Cycles:</b> Contains the number of power cycles.</p>
143:128	<p><b>Power On Hours:</b> Contains the number of power-on hours. This may not include time that the controller was powered and in a non-operational power state.</p>
159:144	<p><b>Unsafe Shutdowns:</b> Contains the number of unsafe shutdowns. This count is incremented when a shutdown notification (CC.SHN) is not received prior to loss of power.</p>
175:160	<p><b>Media and Data Integrity Errors:</b> Contains the number of occurrences where the controller detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum failure, or LBA tag mismatch are included in this field.</p>
191:176	<p><b>Number of Error Information Log Entries:</b> Contains the number of Error Information log entries over the life of the controller.</p>
195:192	<p><b>Warning Composite Temperature Time:</b> Contains the amount of time in minutes that the controller is operational and the Composite Temperature is greater than or equal to the Warning Composite Temperature Threshold (WCTEMP) field and less than the Critical Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.</p> <p>If the value of the WCTEMP or CCTEMP field is 0h, then this field is always cleared to 0h regardless of the Composite Temperature value.</p>
199:196	<p><b>Critical Composite Temperature Time:</b> Contains the amount of time in minutes that the controller is operational and the Composite Temperature is greater than the Critical Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.</p> <p>If the value of the CCTEMP field is 0h, then this field is always cleared to 0h regardless of the Composite Temperature value.</p>
201:200	<p><b>Temperature Sensor 1:</b> Contains the current temperature reported by temperature sensor 1.</p>
203:202	<p><b>Temperature Sensor 2:</b> Contains the current temperature reported by temperature sensor 2.</p>

205:204	<b>Temperature Sensor 3:</b> Contains the current temperature reported by temperature sensor 3.
207:206	<b>Temperature Sensor 4:</b> Contains the current temperature reported by temperature sensor 4.
209:208	<b>Temperature Sensor 5:</b> Contains the current temperature reported by temperature sensor 5.
211:210	<b>Temperature Sensor 6:</b> Contains the current temperature reported by temperature sensor 6.
213:212	<b>Temperature Sensor 7:</b> Contains the current temperature reported by temperature sensor 7.
215:214	<b>Temperature Sensor 8:</b> Contains the current temperature reported by temperature sensor 8.
219:216	<b>Thermal Management Temperature 1 Transition Count:</b> Contains the number of times the controller transitioned to lower power active power states or performed vendor specific thermal management actions while minimizing the impact on performance in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5) (i.e., the Composite Temperature rose above the Thermal Management Temperature 1.) This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented.
223:220	<b>Thermal Management Temperature 2 Transition Count:</b> Contains the number of times the controller transitioned to lower power active power states or performed vendor specific thermal management actions regardless of the impact on performance (e.g., heavy throttling) in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5) (i.e., the Composite Temperature rose above the Thermal Management Temperature 2.) This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented.
227:224	<b>Total Time For Thermal Management Temperature 1:</b> Contains the number of seconds that the controller had transitioned to lower power active power states or performed vendor specific thermal management actions while minimizing the impact on performance in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5). This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented.

<p>231:228</p>	<p><b>Total Time For Thermal Management Temperature 2:</b> Contains the number of seconds that the controller had transitioned to lower power active power states or performed vendor specific thermal management actions regardless of the impact on performance (e.g., heavy throttling) in order to attempt to reduce the Composite Temperature because of the host controlled thermal management feature (refer to section 8.4.5). This counter shall not wrap once it reaches its maximum value. A value of zero, indicates that this transition has never occurred or this field is not implemented.</p>
<p>511:232</p>	<p><b>Reserved</b></p>

The temperature data on iSmart implies built-in or on-board thermal sensor value.

Notes: More detailed health info has been defined by innodisk and will be shown on iSMART V5.3.21 (or later version).



# 7. Part Number Rule

CODE	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21
	D	G	E	U	2	-	0	2	T	D	C	1	E	C	A	E	F	-	X	X	X
Definition																					
Code 1 <sup>st</sup> (Disk)											Code 14 <sup>th</sup> (Operation Temperature)										
D : Disk											C: Standard Grade (0°C ~ +70°C)										
											W: Industrial Grade (-40°C ~ +85°C)										
Code 2 <sup>nd</sup> (Feature set)											Code 15 <sup>th</sup> (Internal control)										
G : EverGreen Series											A~Z: BGA PCB version.										
Code 3 <sup>rd</sup> ~5 <sup>th</sup> (Form factor)											Code 16 <sup>th</sup> (Channel of data transfer)										
EU2: U.2 SSD											Q: Quad Channels										
											E: Eight Channels										
Code 7 <sup>th</sup> ~9 <sup>th</sup> (Capacity)											Code 17 <sup>th</sup> (Flash Type)										
A28: 128GB			B56:256GB			C12:512GB					F: Kioxia 3D TLC										
01T:1TB			02T:2TB																		
Code 10 <sup>th</sup> ~12 <sup>th</sup> (Controller)											Code 18 <sup>th</sup> (Optional Function)										
DC1: PCIE 3TG6-P																					
Code 13 <sup>th</sup> (Flash mode)											Code 19 <sup>th</sup> ~ 21 <sup>st</sup> (Customize code)										
E: 64 Layers 3D TLC																					